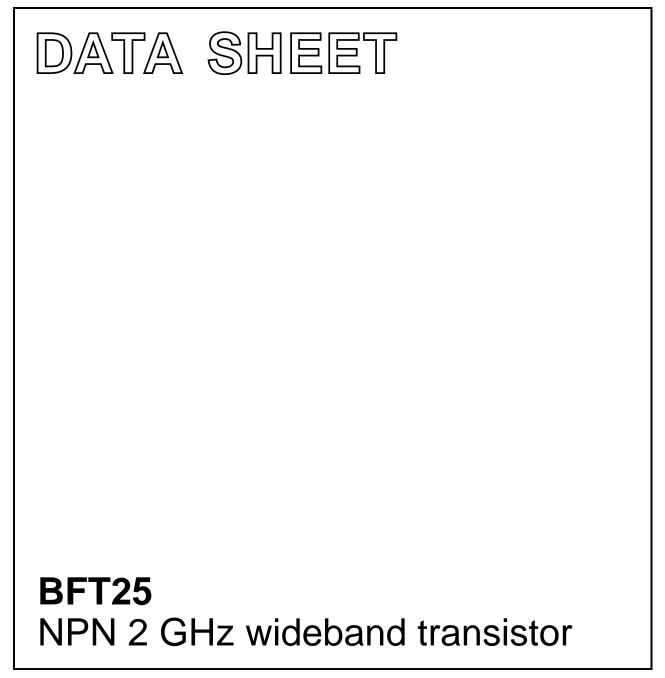
DISCRETE SEMICONDUCTORS



Product specification

November 1992



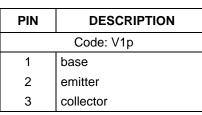
BFT25

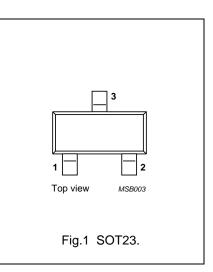
DESCRIPTION

PINNING

NPN transistor in a plastic SOT23 envelope.

It is primarily intended for use in RF low power amplifiers, such as in pocket phones, paging systems, etc. The transistor features low current consumption ($100 \ \mu A$ to $1 \ mA$); due to its high transition frequency, it also has excellent wideband properties and low noise up to high frequencies.





QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	8	V
V _{CEO}	collector-emitter voltage	open base	-	5	V
I _c	DC collector current		-	6.5	mA
P _{tot}	total power dissipation	up to $T_s = 167 \text{ °C}$; note 1	-	30	mW
f _T	transition frequency	I_{C} = 1 mA; V_{CE} = 1 V; f = 500 MHz; T_{amb} = 25 °C	2.3	_	GHz
C _{re}	feedback capacitance	$I_C = 1 \text{ mA}; V_{CE} = 1 \text{ V}; f = 1 \text{ MHz};$ $T_{amb} = 25 ^{\circ}\text{C}$	_	0.45	pF
G _{UM}	maximum unilateral power gain	I_{C} = 1 mA; V_{CE} = 1 V; f = 500 MHz; T_{amb} = 25 °C	18	_	dB
F	noise figure	I_{C} = 1 mA; V_{CE} = 1 V; f = 500 MHz; T_{amb} = 25 °C	3.8	-	dB

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	8	V
V _{CEO}	collector-emitter voltage	open base	-	5	V
V _{EBO}	emitter-base voltage	open collector	-	2	V
I _C	DC collector current		-	6.5	mA
I _{CM}	peak collector current	f > 1 MHz	-	10	mA
P _{tot}	total power dissipation	up to $T_s = 167 \text{ °C}$; note 1	-	30	mW
T _{stg}	storage temperature		-65	150	°C
Tj	junction temperature		-	175	°C

Note

1. T_s is the temperature at the soldering point of the collector tab.

THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	THERMAL RESISTANCE
R _{th j-s}	thermal resistance from junction to soldering point	up to $T_s = 167^{\circ}C$; note 1	260 K/W

Note

1. T_s = is the temperature at the soldering point of the collector tab.

CHARACTERISTICS

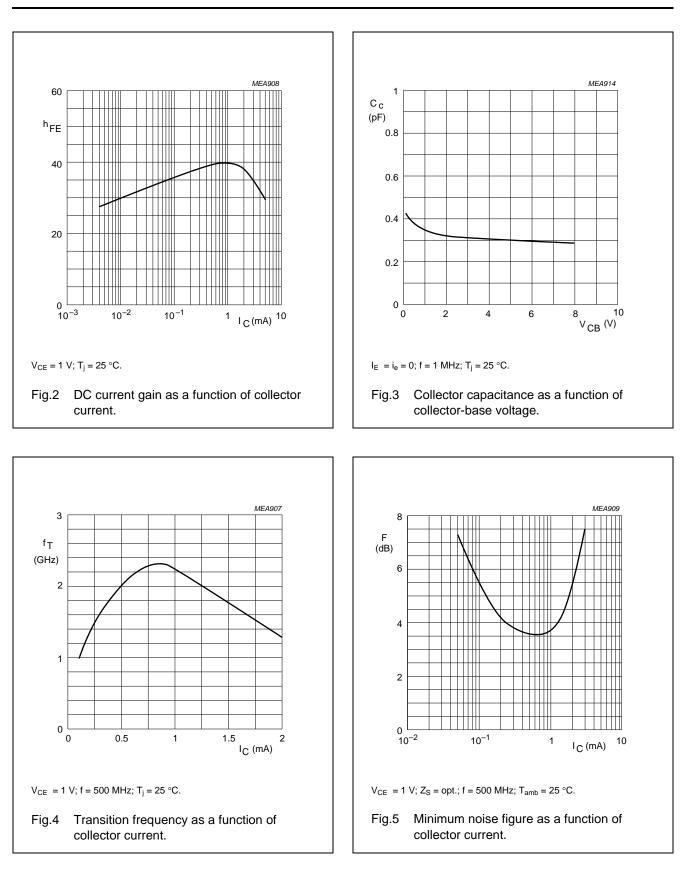
 $T_j = 25 \ ^{\circ}C$ unless otherwise specified.

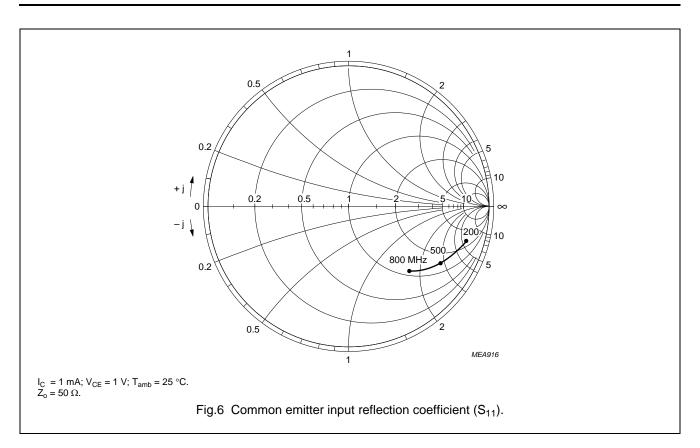
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = 5 V	-	-	50	nA
h _{FE}	DC current gain	$I_{C} = 10 \ \mu A; \ V_{CE} = 1 \ V$	20	30	-	
		I _C = 1 mA; V _{CE} = 1 V	20	40	-	
f _T	transition frequency	I _C = 1 mA; V _{CE} = 1 V; f = 500 MHz	1.2	2.3	-	GHz
C _c	collector capacitance	$I_E = i_e = 0; V_{CB} = 0.5 V; f = 1 MHz$	-	-	0.6	pF
C _e	emitter capacitance	$I_c = i_c = 0; V_{EB} = 0; f = 1 MHz$	-	-	0.5	pF
C _{re}	feedback capacitance	I_{C} = 1 mA; V_{CE} = 1 V; f = 1 MHz; T_{amb} = 25 °C	-	-	0.45	pF
G _{UM}	maximum unilateral power gain (note 1)	I_{C} = 1 mA; V_{CE} = 1 V; f = 500 MHz; T _{amb} = 25 °C	-	18	-	dB
		I_{C} = 1 mA; V_{CE} = 1 V; f = 800 MHz; T _{amb} = 25 °C	-	12	-	dB
F	noise figure	I _C = 0.1 mA; V _{CE} = 1 V; f = 500 MHz; T _{amb} = 25 °C	-	5.5	-	dB
		$I_{C} = 1 \text{ mA}; V_{CE} = 1 \text{ V}; \text{ f} = 500 \text{ MHz}; T_{amb} = 25 \text{ °C}$	_	3.8	-	dB

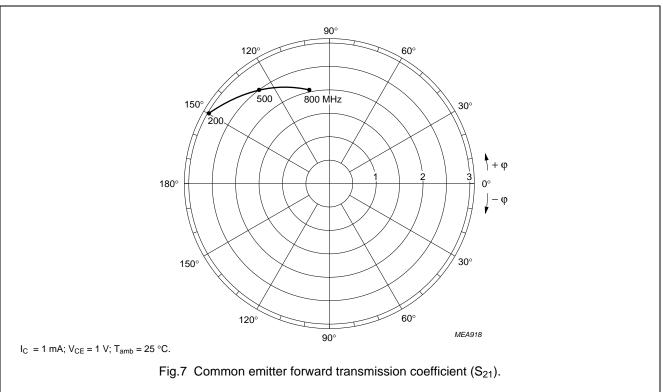
Note

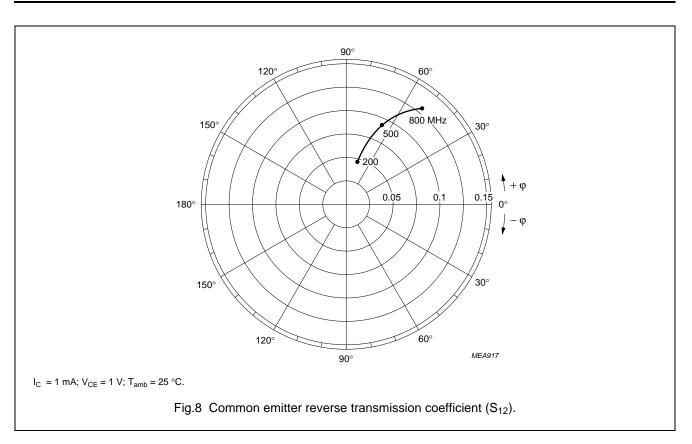
1. G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero and

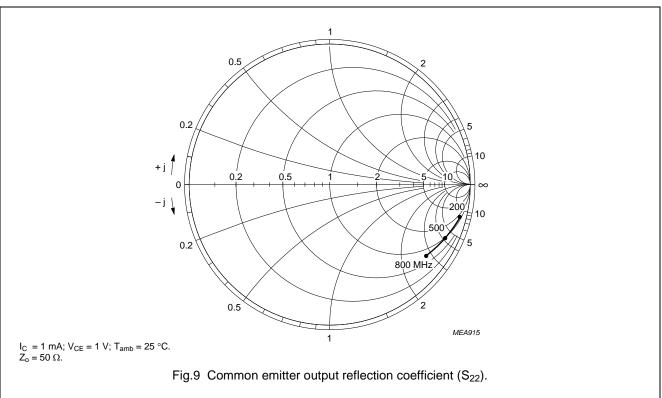
$$G_{UM} = 10 \log \frac{|S_{21}|^2}{(1 - |S_{11}|^2)(1 - |S_{22}|^2)} dB.$$



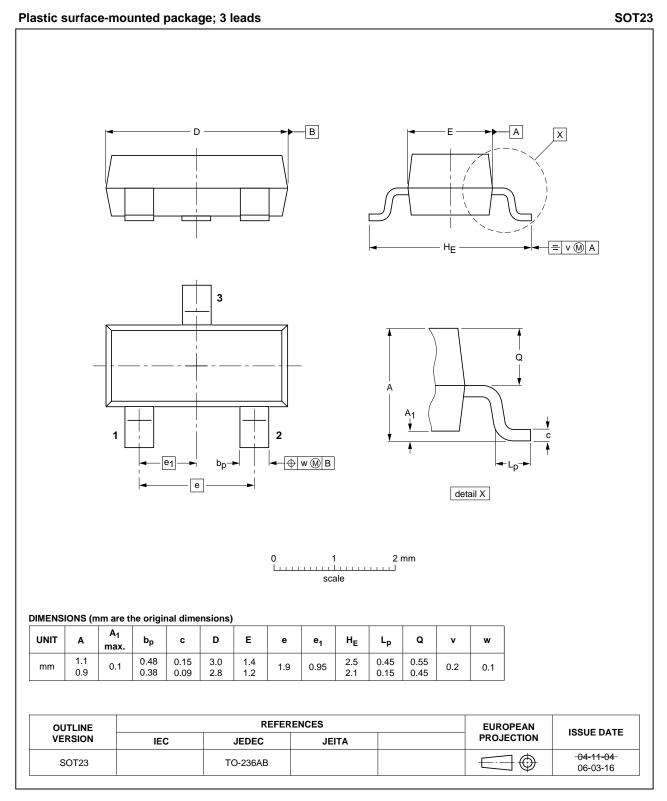








PACKAGE OUTLINE



BFT25

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Contact information

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